NOTES: unless otherwise specified

1.0 Batic an circuit board to conform to P0-001.

Applicable documents

The following items are required.

- PATTERN PLAN / VENDOR DATA: P0-001-EL-004-2006
- DETAIL DRAWING: P0-001-EL-004-2006 THIS DOCUMENT

1.1 Airfoil may not be modified except for process control.

2.0 BASE MATERIAL

2.1 Laminated base material shall be natural color.

See DETAIL A-A for layer types specification and overall thickness.

2.2 S-Shape shall be selected as various design to meet over all board thickness and end item requirements.

3.0 COPPER PLATING

3.1 Copper plating shall have a minimum purity of 99.5 percent and a minimum thickness of 0.01 inch. This also applies to the plating in the holes.

4.0 SOLDERMASK N/A

4.1

5.0 FINISH

5.1 Exposed copper shall be W/V = 3:1 AMERICAN GOLD 3-5A INCH (0.00825-0.00875) OVER ELECTROPLATE 3-0.3-14 1-0.0625 INCH (0.0883-0.2124) THREE TIMES ALCu FC-2221 AND FC-6552 (EN)

6.0 SOLDER SCREEN N/A

6.1

7.0 DIMENSIONS

7.1 All dimensions are in inches.

7.2 Unless otherwise specified all hole sizes apply after plating.

Note sizes are shown in the detail schedule.

8.0 TOLERANCES

8.1 Hole size tolerance ± 003 after plating unless otherwise specified.

8.2 Conductor widths and spacing shall be within 001 of the artwork original.

8.3 Layer to layer registration shall be 007 inches of the worst position.

8.4 Round dimensions shall meet the requirements of the board drawing.

8.5 Width and width shall not exceed that defined in DETAIL A-A.

9.0 APPEARANCE

9.1 All inside and outside corners shall have a minimum radius of 005.

9.2 Remove all laps and smooth sharp edges to 010 max.

Vendor Note: Notice any of the above requirements or if boards cannot be manufactured to meet the above requirements, due to Vendors process and/or techniques or because photo tools and/or specifications are inadequate.